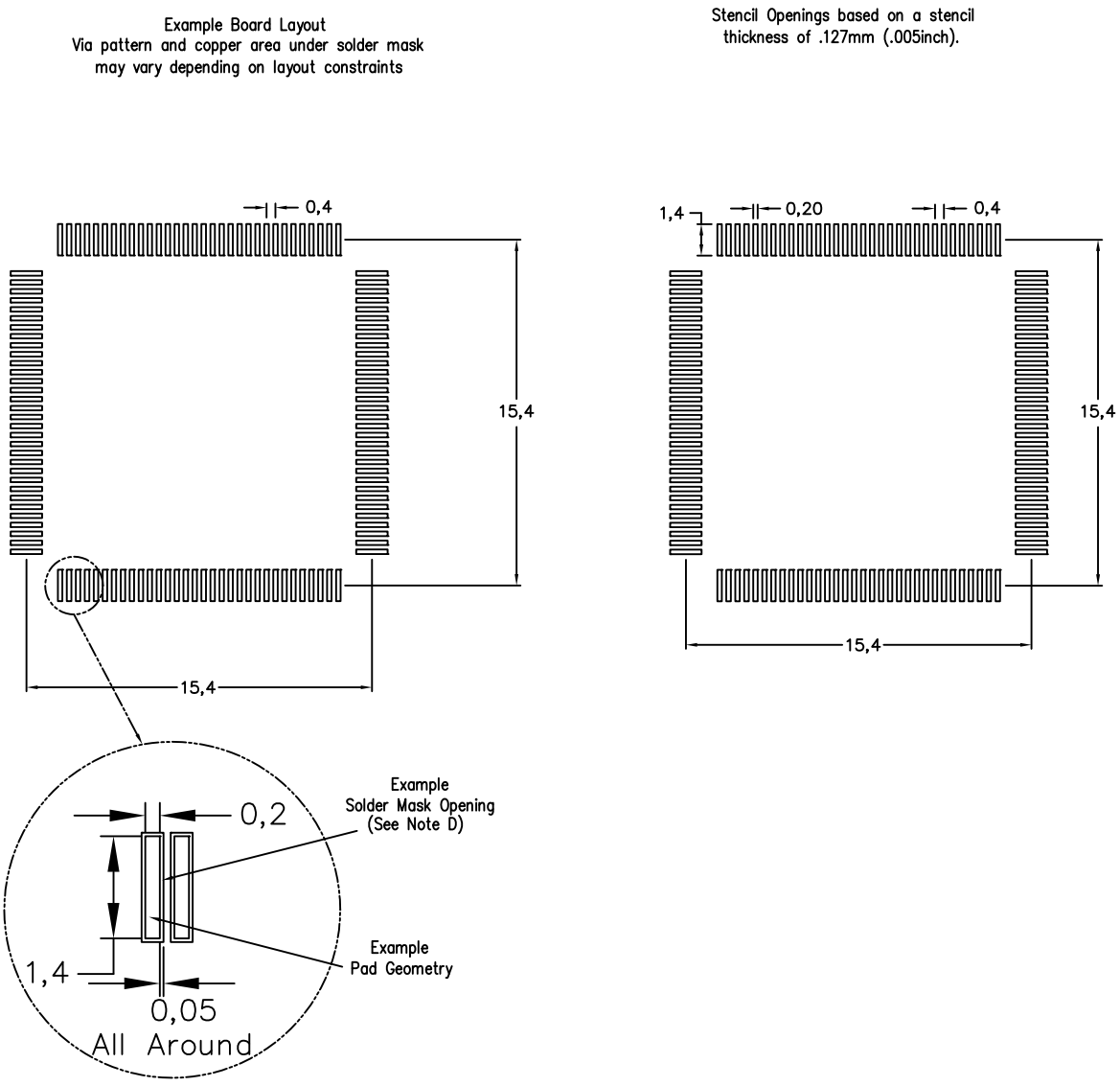
PDT (S–PQFP–G128) PLASTIC QUAD FLAT PACK




NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil metal load solder paste. Refer to IPC–7525 for other stencil recommendations.
D. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265